

ABSTRACT

The present invention relates to a method and apparatus that prevents/minimizes cracking in the ceramic body of processors. The ability to prevent/minimize cracking can ensure successful operation and substantially increase processor lifetime. The present invention discloses a device
5 for maintaining a microprocessor in a desired relationship with a printed wiring board while limiting the transmission of shock and vibrational motion to and from the processor includes a printed wiring board, a processor, and a dynamic isolating mount compressed between the printed wiring board and the processor, wherein the processor maintains the dynamic isolating mount in a compressed state such that the dynamic isolating mount bears on the printed wiring board.